

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A semiconductor device comprising:

a first layer;

a plurality of first test elements which are arranged in the first layer;

a second layer which is ~~adhered to the first layer and~~ is different from the first layer
and which has a first surface and a second surface opposed to the first surface, the first
surface of the second layer being adhered to the first layer; [[and]]

an opening portion which is arranged on the second surface of the second layer; and

a plurality of pads which are arranged in the second layer and are electrically
connected to the first test elements, a part of the pads being exposed from the opening
portion.

Claim 2 (Currently Amended): The device according to claim 1, further comprising:

a plurality of bumps which are respectively arranged on the part of the pads;

a third layer which is adhered to the second layer via the bumps and is different from
the first and second layers; and

solder balls which are arranged on the third layer and electrically connected to the
first test elements.

Claim 3 (Original): The device according to claim 1, wherein all the first test
elements are of the same type.

Claim 4 (Original): The device according to claim 1, wherein the first test elements are arranged in a first line.

Claim 5 (Original): The device according to claim 1, further comprising a plurality of second test elements which are arranged in the first layer and electrically insulated from the pads.

Claim 6 (Original): The device according to claim 5, wherein all the second test elements are of the same type.

Claim 7 (Original): The device according to claim 5, wherein the second test elements are of a type different from the first test elements.

Claim 8 (Original): The device according to claim 5, wherein the first test elements are arranged in a first line, and the second test elements are arranged in a second line different from the first line.

Claim 9 (Original): The device according to claim 5, wherein the second test elements are arranged in the first layer below the pads.

Claim 10 (Original): The device according to claim 1, further comprising:
a first connection member which is arranged in the first layer and connected to the first test elements; and

a second connection member which is arranged in the second layer and connected to the pads and the first connection member.

Claim 11 (Original): The device according to claim 2, further comprising:

a first connection member which is arranged in the first layer and connected to the first test elements;

a second connection member which is arranged in the second layer and connected to the pads and the first connection member; and

a third connection member which is arranged in the third layer and connected to the bumps and the solder balls.

Claims 12-26 (Canceled).